

1Mx4 Bit CMOS Dynamic RAM with Static Column Mode

FEATURES

• Performance range:

	t _{RAC}	t _{CAC}	t _{RC}
KM44C1002A-7	70ns	20ns	130ns
KM44C1002A-8	80ns	20ns	150ns
KM44C1002A-10	100ns	25ns	180ns

- Static Column Mode operation
- \overline{CS} -before- \overline{RAS} Refresh Capability
- \overline{RAS} -only and Hidden Refresh Capability
- 8-bit fast parallel test mode Capability
- TTL compatible Inputs and output
- Early Write or Output Enable Controlled Write
- Single +5V \pm 10% power supply
- 1024 cycles/16ms refresh
- JEDEC standard pinout
- Available In Plastic SOJ, DIP, ZIP

GENERAL DESCRIPTION

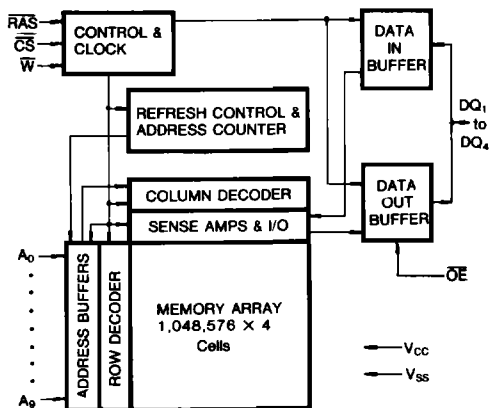
The Samsung KM44C1002A is a high speed CMOS 1,048,576 bit \times 4 Dynamic Random Access Memory. Its design is optimized for high performance applications such as mainframes and mini computers, graphics and high performance microprocessor systems.

The KM44C1002A features Static Column Mode operation which allows high speed random or sequential access within a row. Static Column Mode operation offers high performance while relaxing many critical system timing requirements for fast usable speed.

\overline{CS} -before- \overline{RAS} refresh capability provides on-chip auto refresh as an alternative to \overline{RAS} -only refresh. All inputs and output are fully TTL compatible.

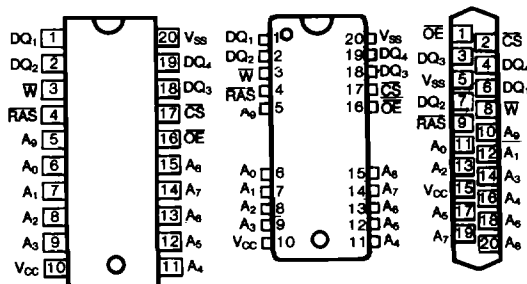
The KM44C1002A is fabricated using Samsung's advanced CMOS process.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION (Top Views)

• KM44C1002AP • KM44C1002AJ • KM44C1002AZ



Pin Name	Pin Function
A0-A9	Address Inputs
DQ1-DQ4	Data In/Out
W	Read/Write Input
OE	Data Output Enable
RAS	Row Address Strobe
CS	Chip Select Input
Vcc	Power (+5V)
Vss	Ground

ABSOLUTE MAXIMUM RATINGS*

Item	Symbol	Rating	Unit
Voltage on Any Pin Relative to V _{SS}	V _{IN} , V _{OUT}	-1 to +7.0	V
Voltage on V _{CC} Supply Relative to V _{SS}	V _{CC}	-1 to +7.0	V
Storage Temperature	T _{stg}	-55 to +150	°C
Power Dissipation	P _D	600	mW
Short Circuit Output Current	I _{OS}	50	mA

* Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded. Functional Operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS (Voltage reference to V_{SS}, T_A=0 to 70°C)

Item	Symbol	Min	Typ	Max	Unit
Supply Voltage	V _{CC}	4.5	5.0	5.5	V
Ground	V _{SS}	0	0	0	V
Input High Voltage	V _{IH}	2.4	—	V _{CC} +1	V
Input Low Voltage	V _{IL}	-1.0	—	0.8	V

DC AND OPERATING CHARACTERISTICS (0°C<T_A<70°C, V_{CC}=5.0V±10%)

(Recommended operating conditions unless otherwise noted)

Parameter		Symbol	Min	Max	Unit
Operating Current* (RAS, CS, Address Cycling @ t _{RC} =min)	KM44C1002A- 7	I _{CC1}	—	105	mA
	KM44C1002A- 8		—	95	mA
	KM44C1002A-10		—	85	mA
Standby Current (RAS=CS=V _{IH})		I _{CC2}	—	2	mA
RAS-Only Refresh Current* (RAS Cycling, CS=V _{IH} , @ t _{RC} =min)	KM44C1002A- 7	I _{CC3}	—	105	mA
	KM44C1002A- 8		—	95	mA
	KM44C1002A-10		—	85	mA
Static Column Mode Current* (RAS=CS=V _{IL} , Address Cycling @ t _{SC} =min)	KM44C1002A- 7	I _{CC4}	—	80	mA
	KM44C1002A- 8		—	70	mA
	KM44C1002A-10		—	60	mA
Standby Current (RAS=CS=V̄ ≥ V _{CC} -0.2V)		I _{CC5}	—	1	mA
CS-Before-RAS Refresh Current* (RAS and CS Cycling @ t _{RC} =min.)	KM44C1002A- 7	I _{CC6}	—	105	mA
	KM44C1002A- 8		—	95	mA
	KM44C1002A-10		—	85	mA
Standby Current (RAS=V _{IH} , CS=V _{IL} , D _{OUT} =Enable)		I _{CC7}	—	5	mA
Input Leakage Current (Any input 0<V _{IN} <6.5V, all other pins not under test=0 volts.)		I _{IL}	-10	10	μA
Output Leakage Current (Data out is disabled, 0V<V _{OUT} <5.5V)		I _{OL}	-10	10	μA
Output High Voltage Level (I _{OH} =-5mA)		V _{OH}	2.4	—	V
Output Low Voltage Level (I _{OL} =4.2mA)		V _{OL}	—	0.4	V

*NOTE: I_{CC1}, I_{CC3}, I_{CC4}, I_{CC6} are dependent on output loading and cycle rates. Specified value are obtained with the output open. I_{CC} is specified as average current. I_{CC1}, I_{CC3}, I_{CC6}, Address can be changed maximum two times while RAS=V_{IL}. I_{CC4}, Address can be changed maximum once while CS=V_{IH}.

CAPACITANCE ($T_A=25^\circ\text{C}$)

Item	Symbol	Min	Max	Unit
Input Capacitance (A_0 - A_9)	C_{IN1}	—	6	pF
Input Capacitance ($\overline{\text{RAS}}$, $\overline{\text{CS}}$, $\overline{\text{W}}$, $\overline{\text{OE}}$)	C_{IN2}	—	7	pF
Output Capacitance (DQ_1 - DQ_4)	C_{OUT}	—	7	pF

AC CHARACTERISTICS ($0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$, $V_{CC}=5.0\text{V} \pm 10\%$, See notes 1,2)

Standard Operation	Symbol	KM44C1002A-7		KM44C1002A-8		KM44C1002A-10		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	130		150		180		ns	
Read-modify-write cycle time	t_{RWC}	185		205		245		ns	
Access time from $\overline{\text{RAS}}$	t_{RAC}		70		80		100	ns	3,4,11
Access time from $\overline{\text{CS}}$	t_{CAC}		20		20		25	ns	3,4,5
Access time from column address	t_{AA}		35		40		50	ns	3,11
$\overline{\text{CS}}$ to output in Low-Z	t_{CLZ}	5		5		5		ns	3,12
Output buffer turn-off delay	t_{OFF}	0	15	0	15	0	20	ns	7
Transition time (rise and fall)	t_T	3	50	3	50	3	50	ns	2
$\overline{\text{RAS}}$ precharge time	t_{RP}	50		60		70		ns	
$\overline{\text{RAS}}$ pulse width	t_{RAS}	70	10,000	80	10,000	100	10,000	ns	
$\overline{\text{RAS}}$ hold time	t_{RSH}	20		20		25		ns	
$\overline{\text{CS}}$ hold time	t_{CSH}	70		80		100		ns	
$\overline{\text{CS}}$ pulse width	t_{CS}	20	10,000	20	10,000	25	10,000	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CS}}$ delay time	t_{RCD}	20	50	20	60	25	75	ns	4
$\overline{\text{RAS}}$ to column address delay time	t_{RAD}	15	35	15	40	20	50	ns	11
$\overline{\text{CS}}$ to $\overline{\text{RAS}}$ precharge time	t_{CRP}	5		5		10		ns	
Row address set-up time	t_{ASR}	0		0		0		ns	
Row address hold time	t_{RAH}	10		10		15		ns	
Column address set-up time	t_{ASC}	0		0		0		ns	
Column address hold time	t_{CAH}	15		15		20		ns	
Column address hold referenced to $\overline{\text{RAS}}$	t_{AR}	55		60		75		ns	
Column Address to $\overline{\text{RAS}}$ lead time	t_{RAL}	35		40		50		ns	
Read command set-up time	t_{RCS}	0		0		0		ns	
Read command hold referenced to $\overline{\text{CS}}$	t_{RCH}	0		0		0		ns	9
Read command hold referenced to $\overline{\text{RAS}}$	t_{RRH}	0		0		0		ns	9
Write command hold time	t_{WCH}	15		15		20		ns	
Write command hold referenced to $\overline{\text{RAS}}$	t_{WCR}	55		60		75		ns	6
Write command pulse width	t_{WP}	15		15		20		ns	

AC CHARACTERISTICS (Continued)

Standard Operation	Symbol	KM44C1002A-7		KM44C1002A-8		KM44C1002A-10		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Write command to \overline{RAS} lead time	t_{RWL}	20		20		25		ns	
Write command to \overline{CS} lead time	t_{CWL}	20		20		25		ns	
Data-in set-up time	t_{DS}	0		0		0		ns	10
Data-in hold time	t_{DH}	15		15		20		ns	10
Data-in hold referenced to \overline{RAS}	t_{DHR}	55		60		75		ns	6
Refresh period (1024 cycles)	t_{REF}		16		16		16	ms	
Write command set-up time	t_{WCS}	0		0		0		ns	8
\overline{CS} to write enable delay time	t_{CWD}	50		50		60		ns	8
\overline{RAS} to write enable delay time	t_{RWD}	100		110		135		ns	8
Column address to \overline{W} delay time	t_{AWD}	65		70		85		ns	8
\overline{CS} setup time (\overline{C} - \overline{B} - \overline{R} refresh)	t_{CSR}	10		10		10		ns	
\overline{CS} hold time (\overline{C} - \overline{B} - \overline{R} refresh)	t_{CHR}	20		30		30		ns	
\overline{RAS} precharge to \overline{CS} hold time	t_{RPC}	10		10		10		ns	
\overline{CS} precharge (\overline{C} - \overline{B} - \overline{R} counter test)	t_{CPT}	35		40		50		ns	
Static column mode cycle time	t_{SC}	40		45		55		ns	
Static column mode read-write cycle time	t_{SRWC}	100		110		135		ns	
Access time from last write	t_{ALW}		65		75		95	ns	3,12
Output data hold time from column address	t_{AOH}	5		5		5		ns	
Output data enable time from \overline{W}	t_{OW}		45		50		70	ns	
\overline{RAS} pulse width (static column mode)	t_{RASC}	70	100,000	80	100,000	100	100,000	ns	
\overline{CS} pulse width (static column mode)	t_{CSC}	20	100,000	20	100,000	25	100,000	ns	
\overline{CS} precharge time (static column mode)	t_{CP}	10		10		10		ns	
Write address hold time reference to \overline{RAS}	t_{AWR}	55		60		75		ns	6
Column address hold time referenced to \overline{RAS} rise	t_{AH}	5		5		10		ns	
Last write to column address delay time	t_{LWAD}	20	30	20	35	25	45	ns	
Last write to column address hold time	t_{AHLW}	65		75		95		ns	
Write command inactive time	t_{WI}	10		10		10		ns	
Write command set-up time (Test mode In)	t_{WTS}	10		10		10		ns	
Write command hold time (Test mode In)	t_{WTH}	10		10		10		ns	
\overline{W} to \overline{RAS} precharge time (\overline{C} - \overline{B} - \overline{R} refresh)	t_{WRP}	10		10		10		ns	
\overline{W} to \overline{RAS} hold time (\overline{C} - \overline{B} - \overline{R} refresh)	t_{WRH}	10		10		10		ns	
\overline{RAS} hold time referenced to \overline{OE}	t_{ROH}	20		20		20		ns	
\overline{OE} access time	t_{OEA}		20		20		25	ns	
\overline{OE} to data delay	t_{OED}	20		20		25		ns	
Output buffer turn off delay time from \overline{OE}	t_{OEZ}	0	20	0	20	0	25	ns	
\overline{OE} command hold time	t_{OEH}	20		20		25		ns	

TEST MODE CYCLE

(Note. 13)

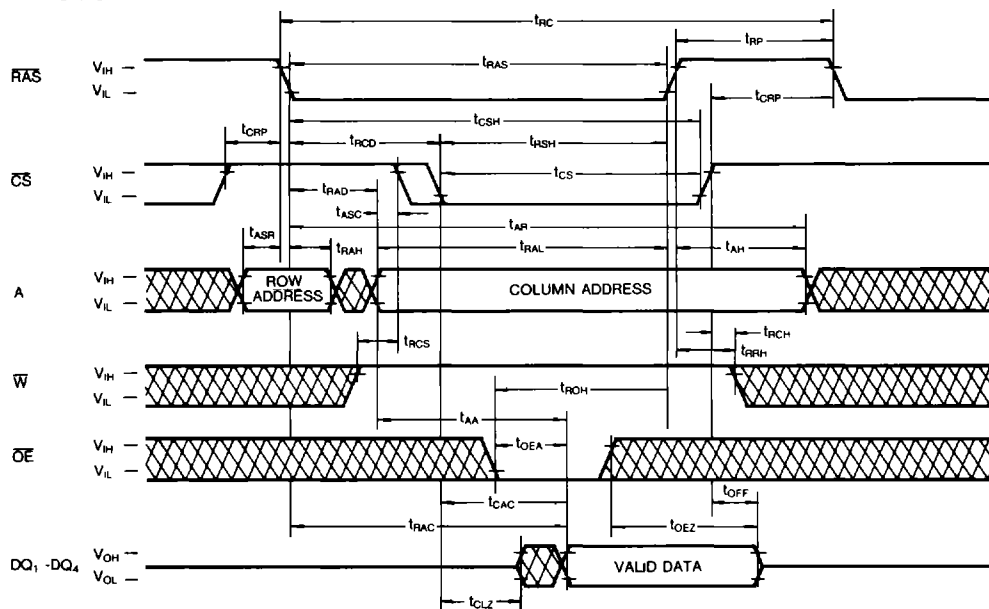
Standard Operation	Symbol	KM44C1002A-7		KM44C1002A-8		KM44C1002A-10		Unit	Notes
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	t _{RC}	135		155		185		ns	
Read-modify-write cycle time	t _{RWC}	185		210		250		ns	
Access time from $\overline{\text{RAS}}$	t _{RAC}		75		85		105	ns	3,4,11
Access time from $\overline{\text{CS}}$	t _{CAC}		25		25		30	ns	3,4,5
Access time from column address	t _{AA}		40		45		55	ns	3,11
$\overline{\text{RAS}}$ pulse width	t _{RAS}	75	10,000	85	10,000	105	10,000	ns	
$\overline{\text{CS}}$ pulse width	t _{CS}	25	10,000	25	10,000	30	10,000	ns	
$\overline{\text{RAS}}$ hold time	t _{RSH}	25		25		30		ns	
$\overline{\text{CS}}$ hold time	t _{CSH}	75		85		105		ns	
Column Address to $\overline{\text{RAS}}$ lead time	t _{RAL}	40		45		55		ns	
$\overline{\text{CS}}$ to write enable delay	t _{CWD}	55		55		65		ns	8
$\overline{\text{RAS}}$ to write enable delay	t _{RWD}	105		115		140		ns	8
Column address to $\overline{\text{W}}$ delay time	t _{AWD}	70		75		90		ns	8
Static column mode cycle time	t _{SC}	45		50		60		ns	
Static column mode read-modify-write	t _{SRWC}	105		115		135		ns	
$\overline{\text{RAS}}$ pulse width (static column mode)	t _{RASC}	75	100,000	85	100,000	105	100,000	ns	
Access time from last write	t _{ALW}		70		80		100	ns	3,12
$\overline{\text{CS}}$ pulse width (static column mode)	t _{CSC}	25	100,000	25	100,000	30	100,000	ns	
$\overline{\text{OE}}$ access time	t _{OEA}		25		25		30	ns	
$\overline{\text{OE}}$ to data delay	t _{OED}	25		25		30		ns	
$\overline{\text{OE}}$ command hold time	t _{OEH}	25		25		30		ns	

NOTES

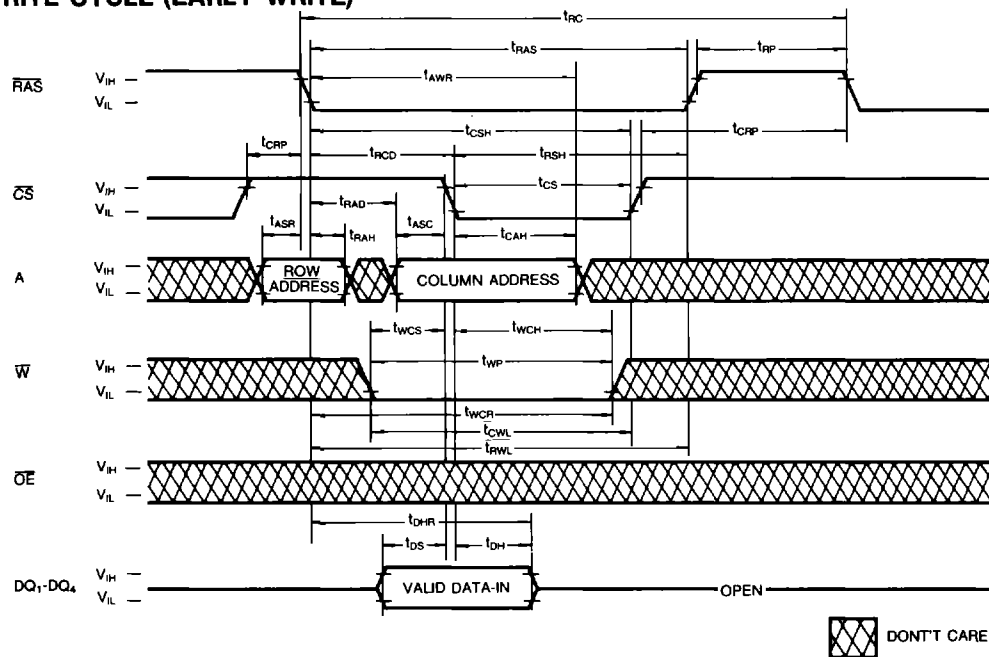
1. An initial pause of 200 μ s is required after power-up followed by any 8 $\overline{\text{CBR}}$ or $\overline{\text{ROR}}$ cycles before proper device operation is achieved.
2. $V_{IH(\min)}$ and $V_{IL(\max)}$ are reference levels for measuring timing of input signals. Transition times are measured between $V_{IH(\min)}$ and $V_{IL(\max)}$, and are assumed to be 5ns for all inputs.
3. Measured with a load equivalent to 2 TTL loads and 100pF
4. Operation within the t_{RCD(max)} limit insures that t_{RAC(max)} can be met. t_{RCD(max)} is specified as a reference point only. If t_{RCD} is greater than the specified t_{RCD(max)} limit, then access time is controlled exclusively by t_{CAC}.
5. Assumes that t_{RCD} > t_{RCD(max)}.
6. t_{AWR}, t_{WCR}, t_{DHR} are referenced to t_{RAD(max)}
7. This parameter defines the time at which the output achieves the open circuit condition and is not referenced to V_{OH} or V_{OL}.
8. t_{WCS}, t_{RWD}, t_{CWD} and t_{AWD} are non restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If t_{WCS} > t_{WCS(min)} the cycle is an early write cycle and the data out pin will remain high impedance for the duration of the cycle. If t_{CWD} > t_{CWD(min)} and t_{RWD} > t_{RWD(min)} and t_{AWD} > t_{AWD(min)}, then the cycle is a read-write cycle and the data out will contain the data read from the selected address. If neither of the above conditions are satisfied, the condition of the data out is indeterminate.
9. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
10. These parameters are referenced to the $\overline{\text{CS}}$ leading edge in early write cycles and to the $\overline{\text{W}}$ leading edge in read-write cycles.
11. Operation within the t_{RAD(max)} limit insures that t_{RAC(max)} can be met. t_{RAD(max)} is specified as a reference point only. If t_{RAD} is greater than the specified t_{RAD(max)} limit, then access time is controlled by t_{AA}.
12. Operation within the t_{LWAD(max)} limit insures that t_{ALW(max)} can be met. t_{LWAD(max)} is specified as a reference point only. t_{LWAD} is greater than the specified t_{LWAD(max)} limit, then access time is controlled by t_{AA}.
13. These specifications are applied in the test mode.

TIMING DIAGRAMS

READ CYCLE

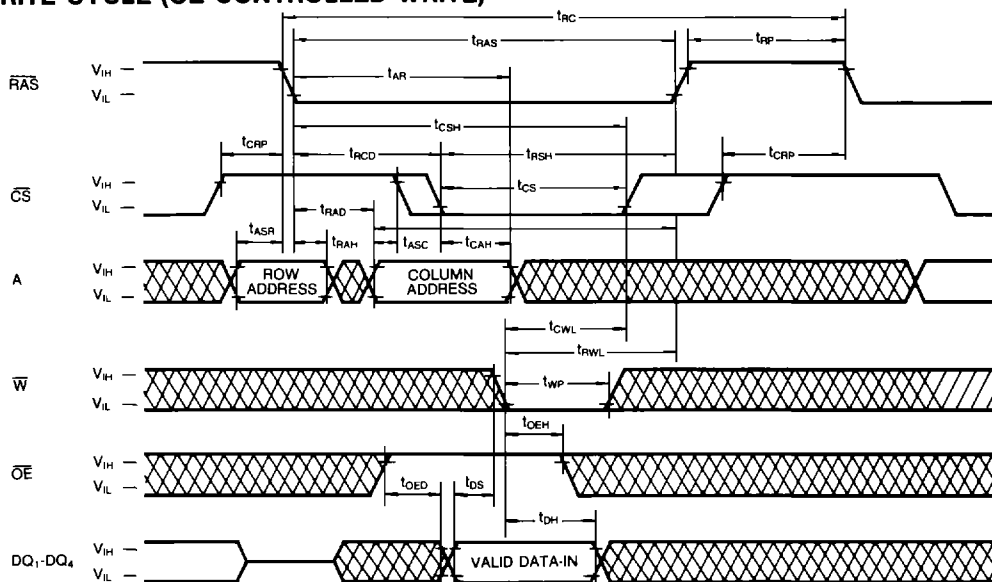


WRITE CYCLE (EARLY WRITE)

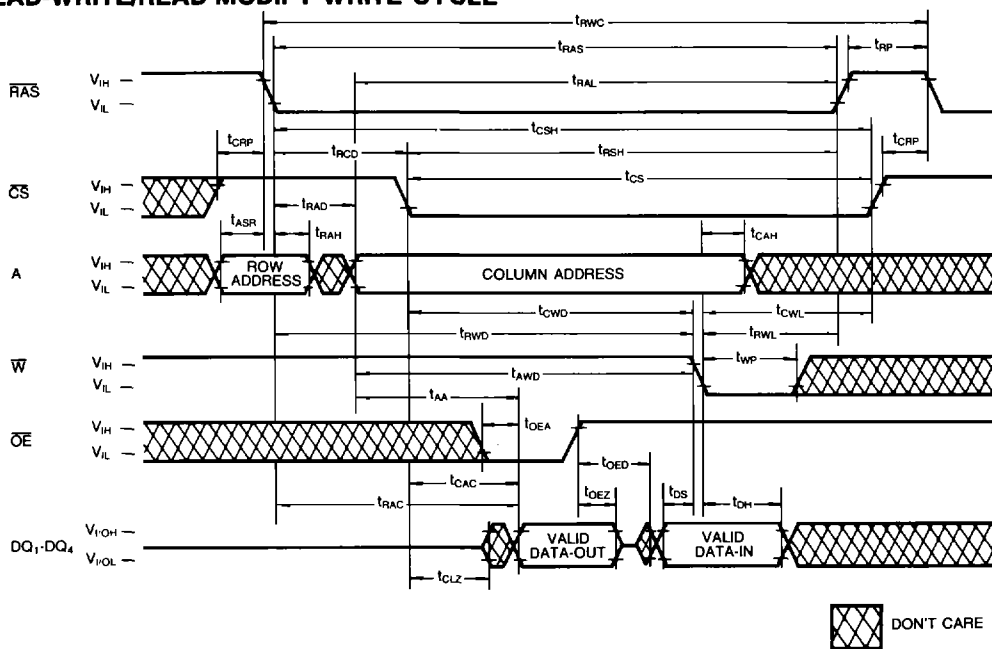


TIMING DIAGRAMS (Continued)

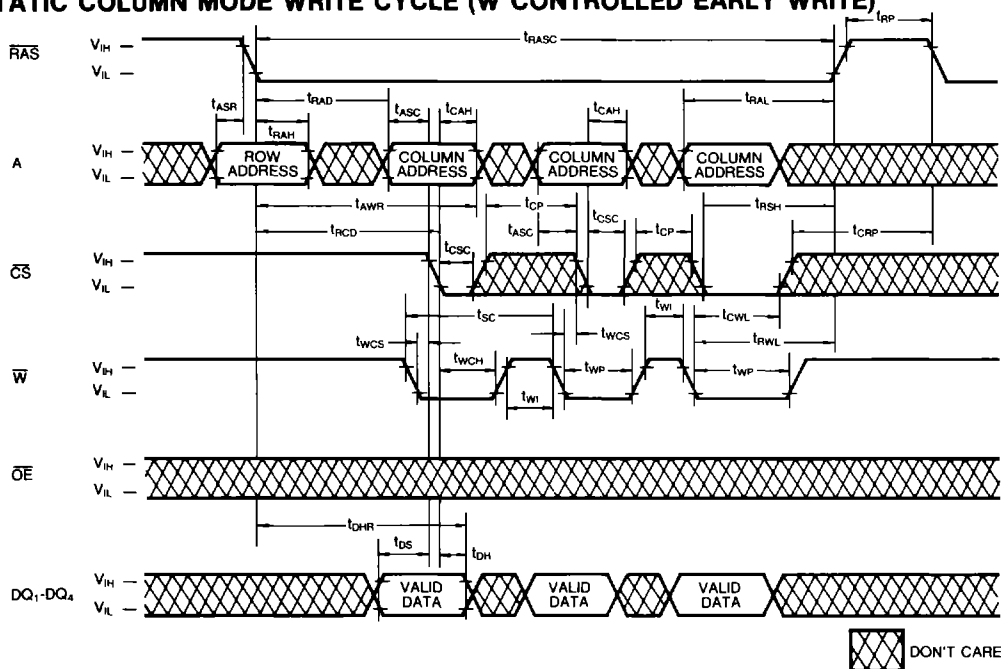
WRITE CYCLE ($\overline{\text{OE}}$ CONTROLLED WRITE)



READ-WRITE/READ-MODIFY-WRITE CYCLE

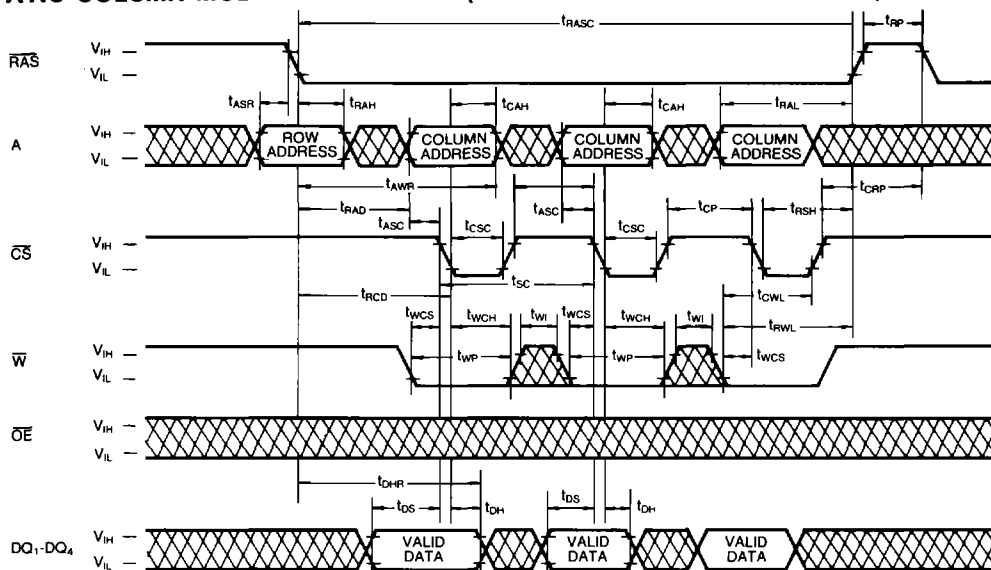


STATIC COLUMN MODE READ CYCLE

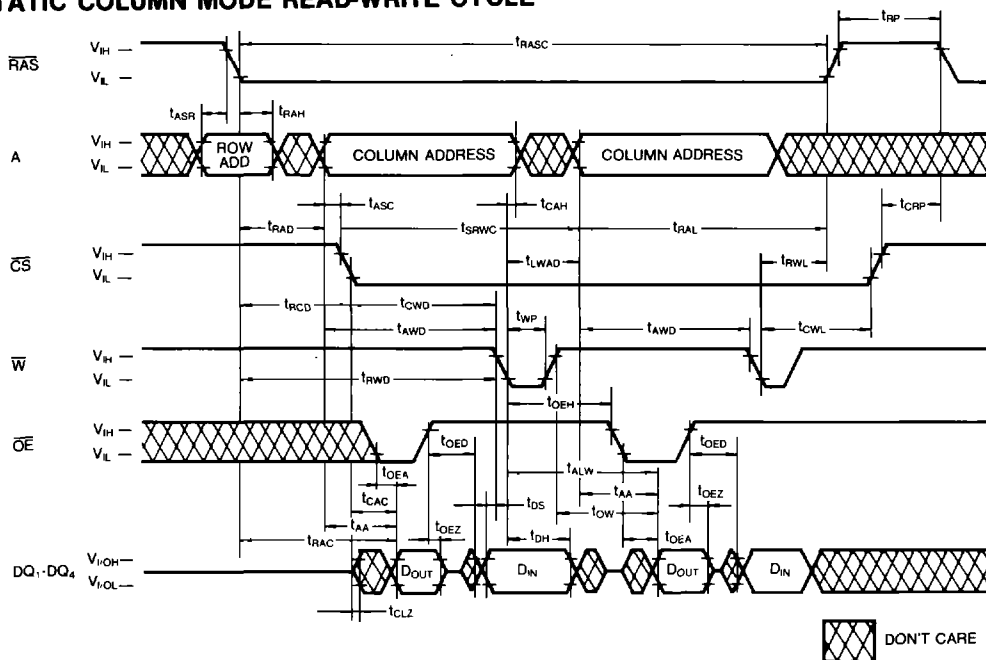


TIMING DIAGRAMS (Continued)

STATIC COLUMN MODE WRITE CYCLE ($\overline{\text{CS}}$ CONTROLLED EARLY WRITE)

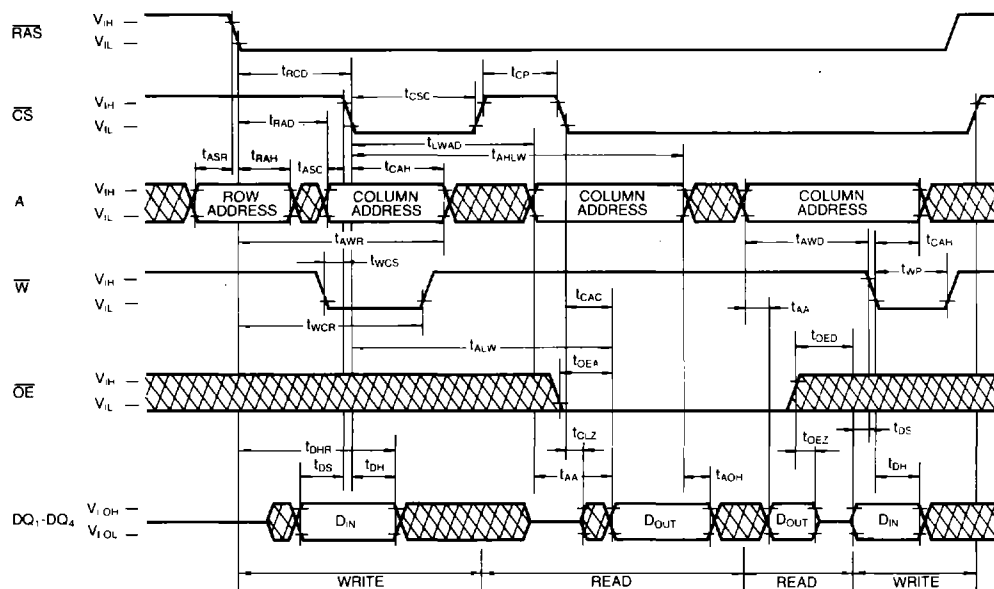


STATIC COLUMN MODE READ-WRITE CYCLE

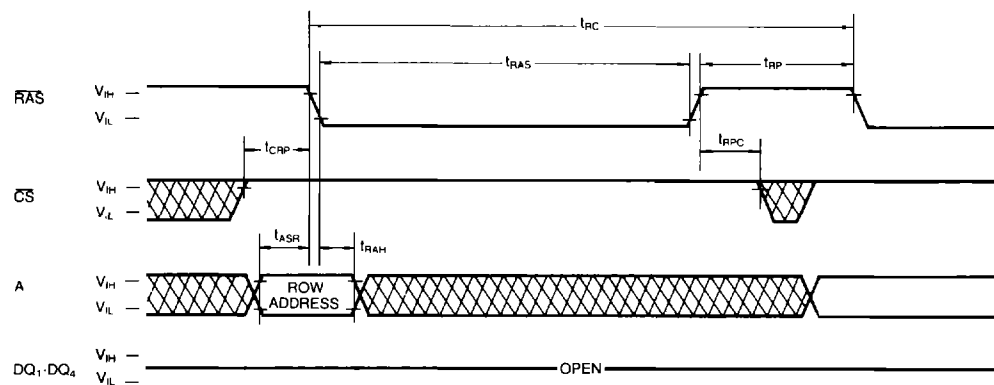


TIMING DIAGRAMS (Continued)

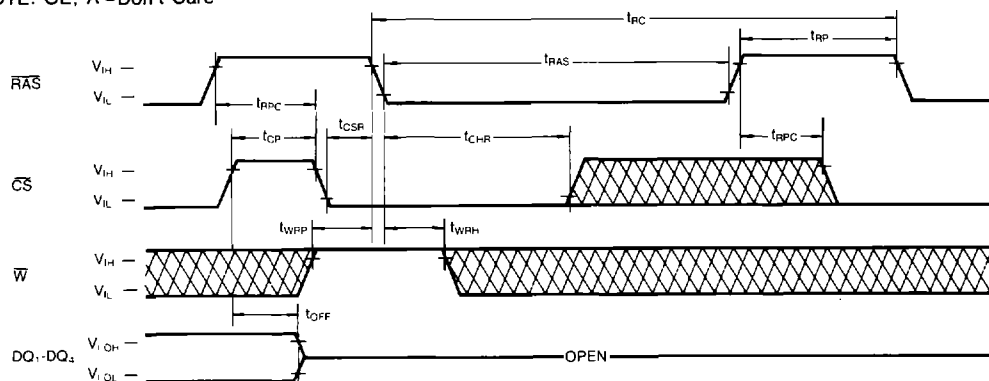
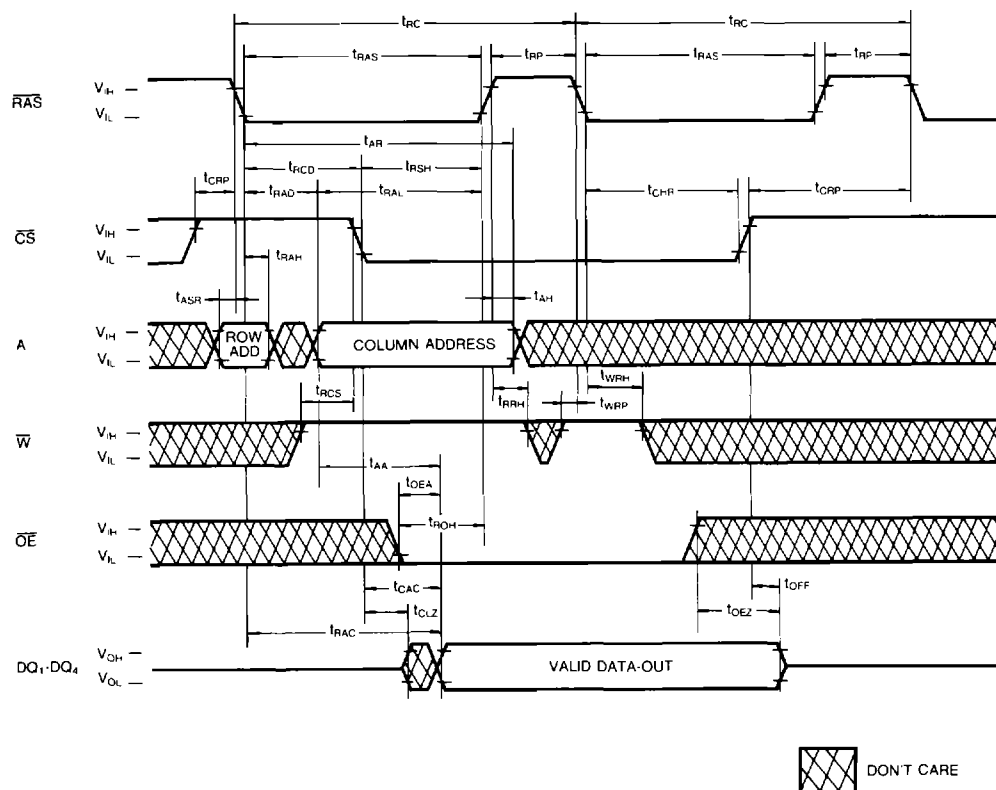
STATIC COLUMN MODE MIXED CYCLE



RAS-ONLY REFRESH CYCLE

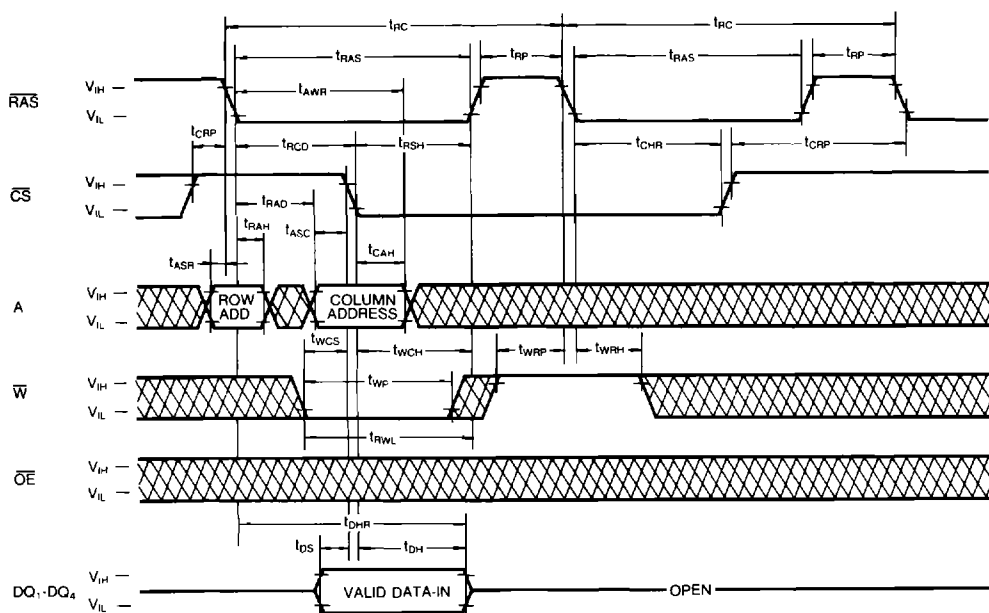
NOTE: \bar{W} , \bar{OE} = Don't Care
 DON'T CARE

TIMING DIAGRAMS (Continued)

 \overline{CS} -BEFORE- \overline{RAS} REFRESH CYCLENOTE: \overline{OE} , A=Don't Care**HIDDEN REFRESH CYCLE (READ)**

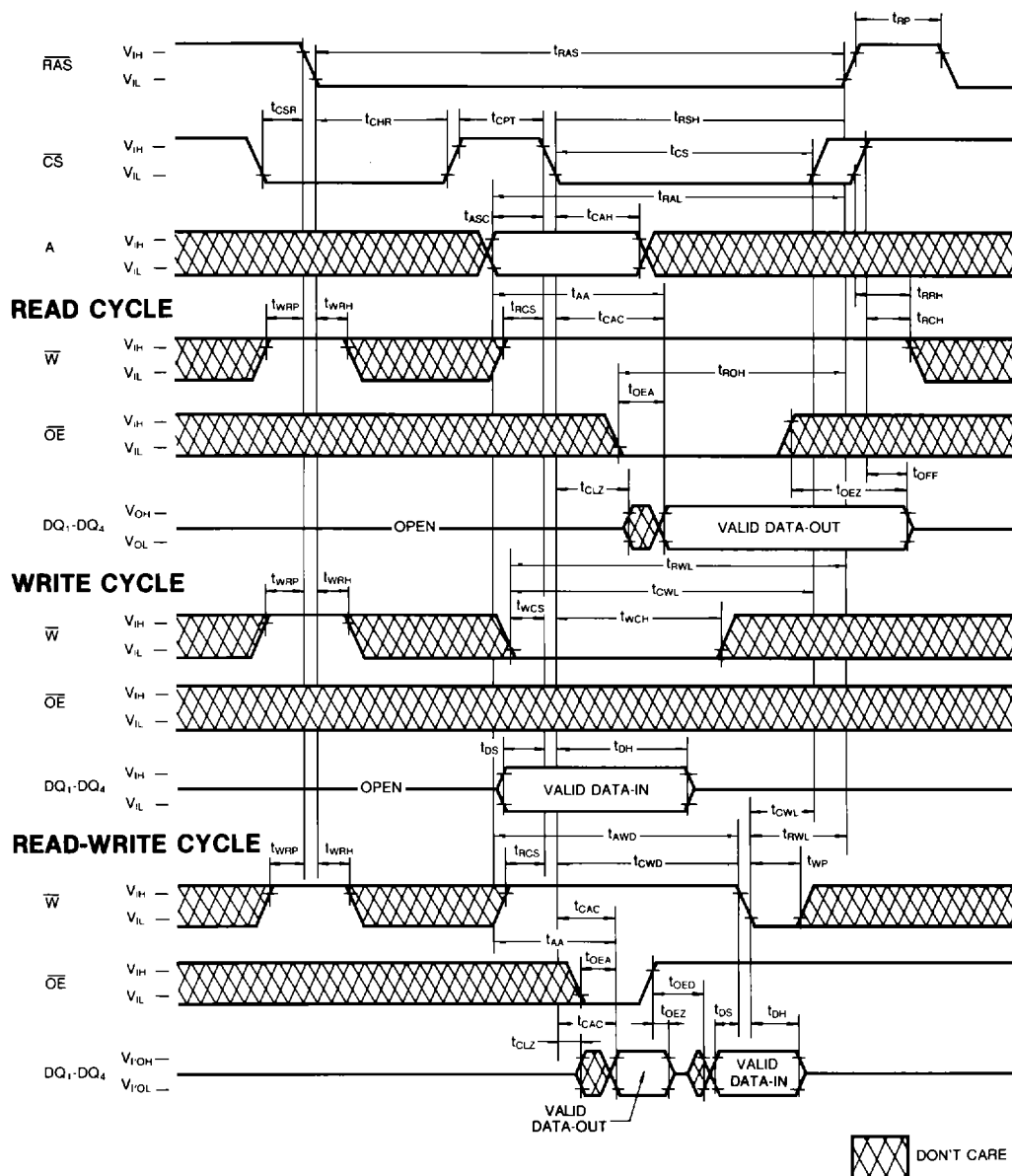
TIMING DIAGRAMS (Continued)

HIDDEN REFRESH CYCLE (WRITE)


 DON'T CARE

TIMING DIAGRAMS (Continued)

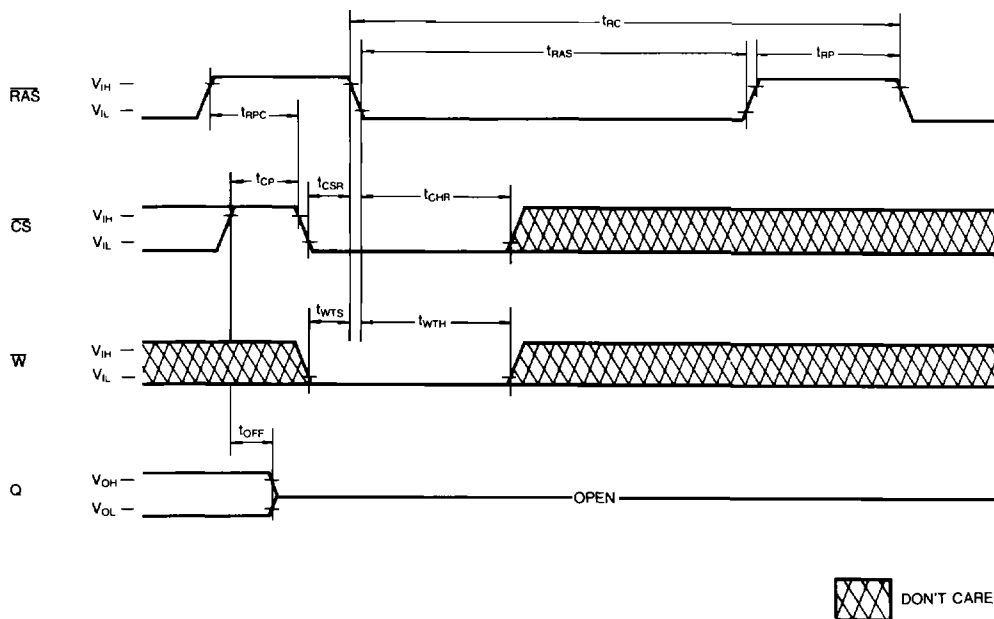
CS-BEFORE-RAS REFRESH COUNTER TEST CYCLE



TIMING DIAGRAMS (Continued)

TEST MODE IN CYCLE

NOTE: D, Address=Don't Care



TEST MODE DESCRIPTION

The KM44C1002A is the RAM organized 1,048,576 words by 4 bit, it is internally organized 524,288 words by 8 bits. In "Test Mode", data are written into 8 sectors in parallel and retrieved the same way. Column address bit A_0 is not used. If, upon reading, two bits on one I/O pin are equal (all "1"s or "0"s), the I/O pin indicates a "1". If they were not equal, the I/O pin would

indicate a "0". In "Test Mode", the 1M \times 4 DRAM can be tested as if it were a 512K \times 4 DRAM. $\overline{\text{W}}$, $\overline{\text{CS}}$ Before $\overline{\text{RAS}}$ Cycle (Test Mode in Cycle) puts the device into "Test Mode". And " $\overline{\text{CS}}$ Before $\overline{\text{RAS}}$ Refresh Cycle" or " $\overline{\text{RAS}}$ only Refresh Cycle" puts it back into "Normal Mode". The "Test Mode" function reduces test time (1/2 in cases of N test pattern).

DEVICE OPERATIONS

Device Operation

The KM44C1002A contains 4,194,304 memory locations organized as 1,048,576 four-bit words. Twenty address bits are required to address a particular 4-bit word in the memory location. Since the KM44C1002A has only 10 address input pins, time multiplexed addressing is used to input 10 row and 10 column addresses. The multiplexing is controlled by the timing relationship between the row address strobe ($\overline{\text{RAS}}$), the chip select input ($\overline{\text{CS}}$) and the valid row and column address inputs.

Operating of the KM44C1002A begins by strobing in a valid row address with $\overline{\text{RAS}}$ while $\overline{\text{CS}}$ remains high. Then the address on the 10 address input pins is changed from a row address to a column address and is strobed in by $\overline{\text{CS}}$. This is the beginning of any KM44C1002A cycle in which a memory location is accessed. The specific type of cycle is determined by the state of the write enable pin and various timing relationships. The cycle is terminated when both $\overline{\text{RAS}}$ and $\overline{\text{CS}}$ have returned to the high state. Another cycle can be initiated after $\overline{\text{RAS}}$ remains high long enough to satisfy the $\overline{\text{RAS}}$ precharge time (t_{RP}) requirement.

$\overline{\text{RAS}}$ and $\overline{\text{CS}}$ Timing

The minimum $\overline{\text{RAS}}$ and $\overline{\text{CS}}$ pulse widths are specified by $t_{\text{RAS}}(\text{min})$ and $t_{\text{CS}}(\text{min})$ respectively. These minimum pulse widths must be satisfied for proper device operation and data integrity. Once a cycle is initiated by bringing $\overline{\text{RAS}}$ low, it must not be aborted prior to satisfying the minimum $\overline{\text{RAS}}$ and $\overline{\text{CS}}$ pulse widths. In addition, a new cycle must not begin until the minimum $\overline{\text{RAS}}$ precharge time, t_{RP} , has been satisfied. Once a cycle begins, internal clocks and other circuits within the KM44C1002A begin a complex sequence of events. If the sequence is broken by violating minimum timing requirements, loss of data integrity can occur.

Read

A read cycle is achieved by maintaining the write enable input($\overline{\text{W}}$) high during a $\overline{\text{RAS}}/\overline{\text{CS}}$ cycle. The access time is normally specified with respect to the falling edge of $\overline{\text{RAS}}$. But the access time also depends on the falling edge of $\overline{\text{CS}}$ and on the valid column address transition.

If $\overline{\text{CS}}$ goes low before $t_{\text{RCD}}(\text{max})$ and if the column address is valid before $t_{\text{RAD}}(\text{max})$ then the access time to valid data is specified by $t_{\text{RAC}}(\text{min})$. However, if $\overline{\text{CS}}$ goes low after $t_{\text{RCD}}(\text{max})$ or if the column address becomes valid after $t_{\text{RAD}}(\text{max})$, access is specified by t_{CAC} or t_{AA} . In order to achieve the minimum access time, $t_{\text{RAC}}(\text{min})$, it is necessary to meet both $t_{\text{RCD}}(\text{max})$ and $t_{\text{RAD}}(\text{max})$.

The KM44C1002A has common data I/O pins. For this reason and output enable control input ($\overline{\text{OE}}$) has been

provided so the output buffer can be precisely controlled. For data to appear at the outputs, $\overline{\text{OE}}$ must be low for the period of time defined by t_{OEA} and t_{OEZ} .

Write

The KM44C1002A can perform early write, late write and read-modify-write cycles. The difference between these cycles is in the state of data-out and is determined by the timing relationship between $\overline{\text{W}}$, $\overline{\text{OE}}$ and $\overline{\text{CS}}$. In any type of write cycle, Data-in must be valid at or before the falling edge of $\overline{\text{W}}$ or $\overline{\text{CS}}$, whichever is later.

Early Write: An early write cycle is performed by bringing $\overline{\text{W}}$ low before $\overline{\text{CS}}$. The 4-bit wide data at the data input pins is written into the addressed memory cells. Throughout the early write cycle the output remains in the Hi-Z state. In the early write cycle the output buffers remain in the Hi-Z state regardless of the state of the $\overline{\text{OE}}$ input.

Read-Modify-Write: In this cycle, valid data from the addressed cell appears at the output before and during the time that data is being written into the same cell location. This cycle is achieved by bringing $\overline{\text{W}}$ low after $\overline{\text{CS}}$ and meeting the data sheet read-modify-write cycle timing requirements. The output enable input ($\overline{\text{OE}}$) must be low during the time defined by t_{OEA} and t_{OEZ} for data to appear at the output. If t_{CWD} and t_{RWD} are not met the output may contain invalid data. Conforming to the $\overline{\text{OE}}$ timing requirement prevents bus contention on the KM44C1002A's DQ pins.

Data Output

The KM44C1002A has a three-state output buffer which is controlled by $\overline{\text{CS}}$ and $\overline{\text{OE}}$. Whenever $\overline{\text{CS}}$ or $\overline{\text{OE}}$ is high (V_{IH}) the output is in the high impedance (Hi-Z) state. In any cycle in which valid data appears at the output the output goes into the low impedance state in a time specified by t_{CLZ} after the falling edge of $\overline{\text{CS}}$. Invalid data may be present at the output during the time after t_{CLZ} and before the valid data appears at the output. The timing parameters t_{CAC} , t_{RAC} and t_{AA} specify when the valid data will be present at the output. This is true even if a new $\overline{\text{RAS}}$ cycle occurs (as in hidden refresh). Each of the KM44C1002A operating cycles is listed below after the corresponding output state produced by the cycle.

Valid Output Data: Read, Read-Modify-Write, Hidden Refresh, Static Column Read, Static Column Mode Read-Modify-Write.

Hi-Z Output State: Early Write, $\overline{\text{RAS}}$ -only Refresh, Static Column Mode Write, $\overline{\text{CS}}$ -before- $\overline{\text{RAS}}$ Refresh, $\overline{\text{CS}}$ -only cycle, $\overline{\text{OE}}$ Controlled write.

Indeterminate Output State: Delayed Write

DEVICE OPERATIONS (Continued)

Refresh

The data in the KM44C1002A is stored on a tiny capacitor within each memory cell. Due to leakage the data may leak off after a period of time. To maintain data integrity it is necessary to refresh each of the rows every 16 ms. There are several ways to accomplish this.

\overline{RAS} -Only Refresh: This is the most common method for performing refresh. It is performed by strobing in a row address with \overline{RAS} while \overline{CS} remains high. This cycle must be repeated for each row.

\overline{CS} -before- \overline{RAS} Refresh: The KM44C1002A has \overline{CS} -before- \overline{RAS} on-chip refresh capability that eliminates the need for external refresh addresses. If \overline{CS} is held low for the specified set up time (t_{CSR}) before \overline{RAS} goes low, the on-chip refresh circuitry is enabled. An internal refresh operation automatically occurs. The refresh address is supplied by the on-chip refresh address counter which is then internally incremented in preparation for the next \overline{CS} -before- \overline{RAS} refresh cycle.

Hidden Refresh: A hidden refresh cycle may be performed while maintaining the latest valid data at the output by extending the \overline{CS} active time and cycling \overline{RAS} . The KM44C1002A hidden refresh cycle is actually a \overline{CS} -before- \overline{RAS} refresh cycle within an extended read cycle. The refresh row address is provided by the on-chip refresh address counter.

Other Refresh Methods: It is also possible to refresh the KM44C1002A by using read, write or read-modify-write cycles. Whenever a row is accessed, all the cells in that row are automatically refreshed. There are certain applications in which it might be advantageous to perform refresh in this manner but in general \overline{RAS} -only or \overline{CS} -before- \overline{RAS} refresh is the preferred method.

Static Column Mode

Static Column Mode allows high speed read, write or read-modify-write random access to all the memory cells within a selected row. Operation within a selected row is similar to a static RAM. The read, write or readmodify-write cycles may be mixed in any order.

A Static Column mode read cycle starts as a normal cycle. Additional cells within the selected row are written by applying a new column address while $\overline{W}=V_{IH}$ and $\overline{RAS}=V_{IL}$.

A Static Column mode write cycle starts as a normal cycle. Additional cells within the selected row are written by applying a new column address while $\overline{RAS}=V_{IL}$ and toggling either \overline{W} or \overline{CS} . The data is written into the cell triggered by the latter fallin edge of \overline{W} or \overline{CS} .

\overline{CS} -before- \overline{RAS} Refresh Counter Test Cycle

A special timing sequence using the \overline{CS} -before- \overline{RAS} refresh counter test cycle provides a convenient method of verifying the functionality of the \overline{CS} -before- \overline{RAS} refresh activated circuitry.

After the \overline{CS} -before- \overline{RAS} refresh operation, \overline{CS} goes high and then low again while \overline{RAS} is held low, the read and write operations are enabled.

This is shown in the \overline{CS} -before- \overline{RAS} counter test cycle timing diagram. A memory cell can be addressed with 10 row address bits and 10 column address bits defined as follows:

Row Address—Bits A_0 through A_9 are supplied by the on-chip refresh counter.

Column Address—Bits A_0 through A_9 are strobed-in by the falling edge of \overline{CS} as in a normal memory cycle.

Suggested \overline{CS} -before- \overline{RAS} Counter Test Procedure

The \overline{CS} -before- \overline{RAS} refresh counter test cycle timing is used in each of the following steps:

1. Initialize the internal refresh counter by performing 8 cycles.
2. Write a test pattern of "lows" into the memory cells at a single column address and 1024 row address. (The row addresses are supplied by the on-chip refresh counter).
3. Using read-modify-write cycles, read the "lows" written during step 2 and write "highs" into the same memory locations. Perform this step 512 times so that highs are written into the 512 memory cells.
4. Read the "highs" written during step 3.
5. Complement the test pattern and repeat steps 2, 3 and 4.

Power-up

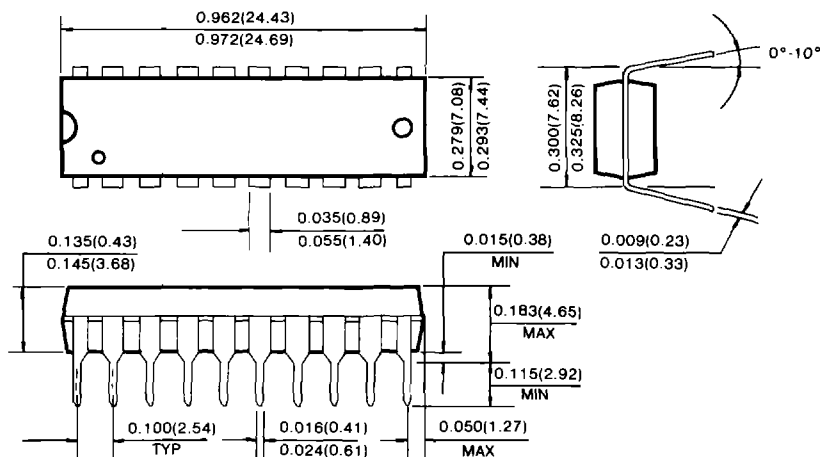
If $\overline{RAS}=V_{SS}$ during power-up, the KM44C1002A could begin an active cycle. This condition results in higher than necessary current demands from the power supply during power-up. It is recommended that \overline{RAS} and \overline{CS} track with V_{CC} during power-up or be held at a valid V_{IH} in order to minimize the power-up current.

An initial pause of 200 μ s is required after power-up followed by any 8 \overline{RAS} cycle before proper device operation is achieved.

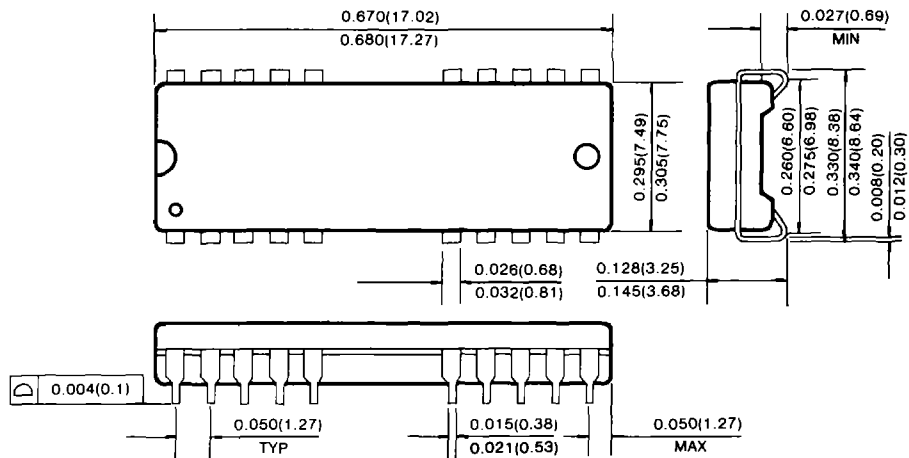
PACKAGE DIMENSIONS

20-LEAD PLASTIC DUAL IN-LINE PACKAGE

Unit: Inches (Millimeters)



20-LEAD PLASTIC SMALL OUT-LINE J-LEAD



PACKAGE DIMENSIONS (Continued)

20-LEAD PLASTIC ZIGZAG-IN-LINE PACKAGE

Units: Inches (millimeters)

